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4.7mm HOUSING FOR LED LAMP WITH WIRE

Part Number: WP1533AA/SRD-W152

Super Bright Red

Features Description • Outstanding material efficiency. The Super Bright Red source color devices are made with Reliable and rugged. Gallium Aluminum Arsenide Red Light Emitting Diode. • Low current capability. • Housing UL rating:94V-0. • Housing material: type 66 nylon. RoHS compliant. **Package Dimensions** Fig.1 : ANODE LEAD :RED INSULATION LEAD ,24 AWG ,UL#1007,ø1.45mm, TINNED OVERCOATED WIRE , STRIP 12.7mm. Fig. 2 : CATHODE LEAD :BLACK INSULATION LEAD ,24 AWG,UL#1007 ,ø1.45mm, TINNED OVERCOATED WIRE , STRIP 12.7mm. Fig.3 : STAKING TO FIX THE HOLDER AND LED . .236] 6[.024] .157] 0.9[.035] ø6[. , , , , , , , Fig.1 0 0 2 2 .9[.272 0 49 Fig.2 12.7[.5] TYP 152.4[6.0]TYP. 11.2[.441] 4[.157]±0.3 Remark: Recommended panel mount hole diameter φ =6.30-6.35mm; panel thickness 1.0mm. Notes: 1. All dimensions are in millimeters (inches). 2. Tolerance is ±0.25(0.01") unless otherwise noted. Lead spacing is measured where the leads emerge from the package. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice. SPEC NO: DSAF3513 **REV NO: V.5** DATE: APR/07/2011

APPROVED: WYNEC

CHECKED: Allen Liu

DATE: APR/07/2011 DRAWN: J.Yu PAGE: 1 OF 5 ERP: 1102007574

Selection Guide

Part No.	Dice	Dice Lens Type Iv (mcd) [2] @ 20mA		<i>,</i> - -	Viewing Angle [1]	
			Min.	Тур.	201/2	
WP1533AA/SRD-W152	Super Bright Red (GaAlAs)	Red Diffused	400	700	60°	

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Red	660		nm	IF=20mA
λD [1]	Dominant Wavelength	Super Bright Red	640		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Red	20		nm	I⊧=20mA
С	Capacitance	Super Bright Red	45		pF	VF=0V;f=1MHz
Vf [2]	Forward Voltage	Super Bright Red	1.85	2.5	V	I⊧=20mA
lr	Reverse Current	Super Bright Red		10	uA	VR = 5V

Notes:

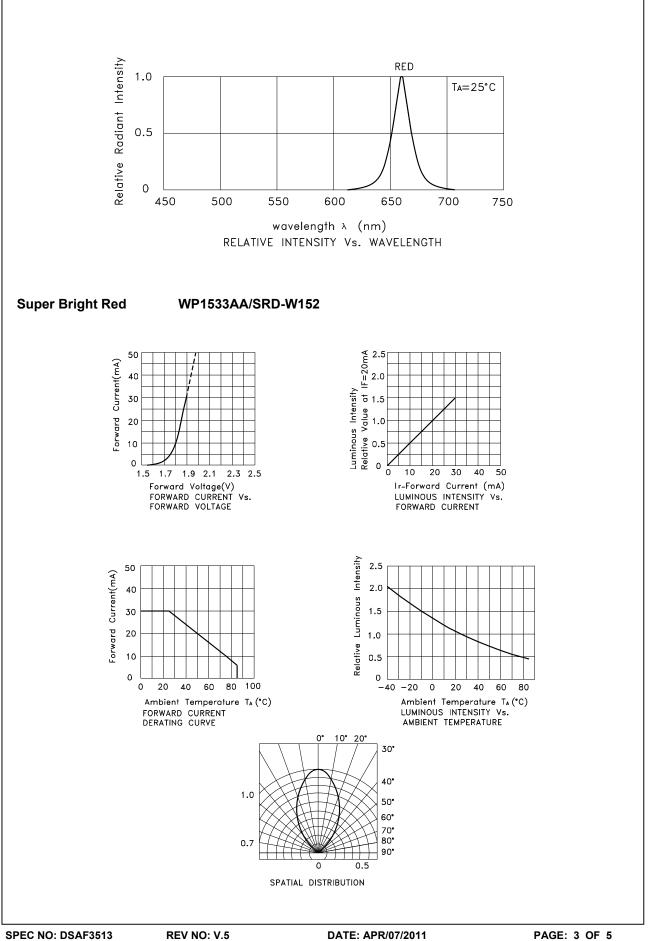
1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

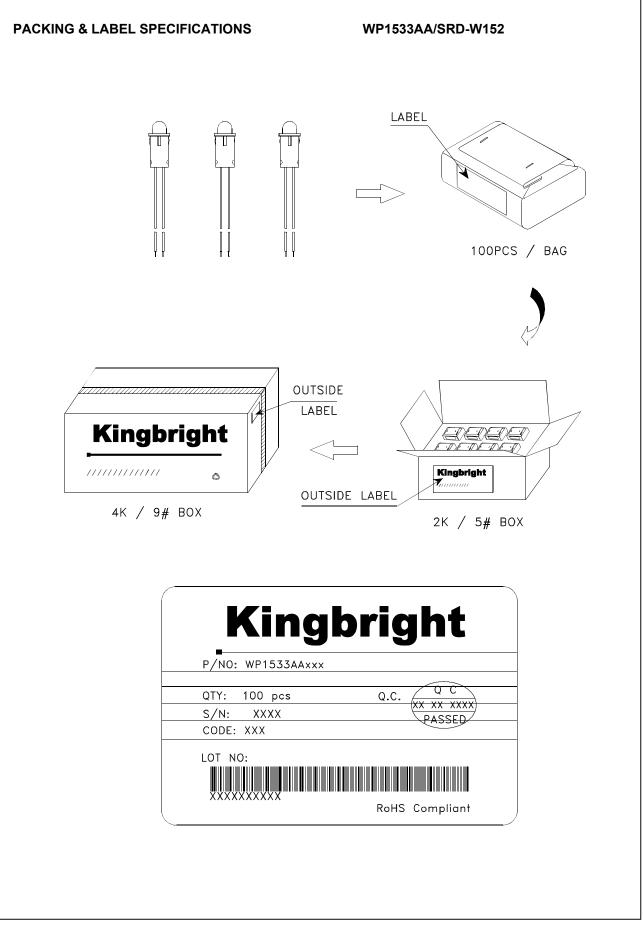
Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Red	Units	
Power dissipation	75	mW	
DC Forward Current	30		
Peak Forward Current [1]	155	mA	
Reverse Voltage	5	V	
Operating/Storage Temperature	-40°C To +85°C		
Lead Solder Temperature [2]	260°C For 3 Seconds		
Lead Solder Temperature [3]	260°C For 5 Seconds		

Notes:

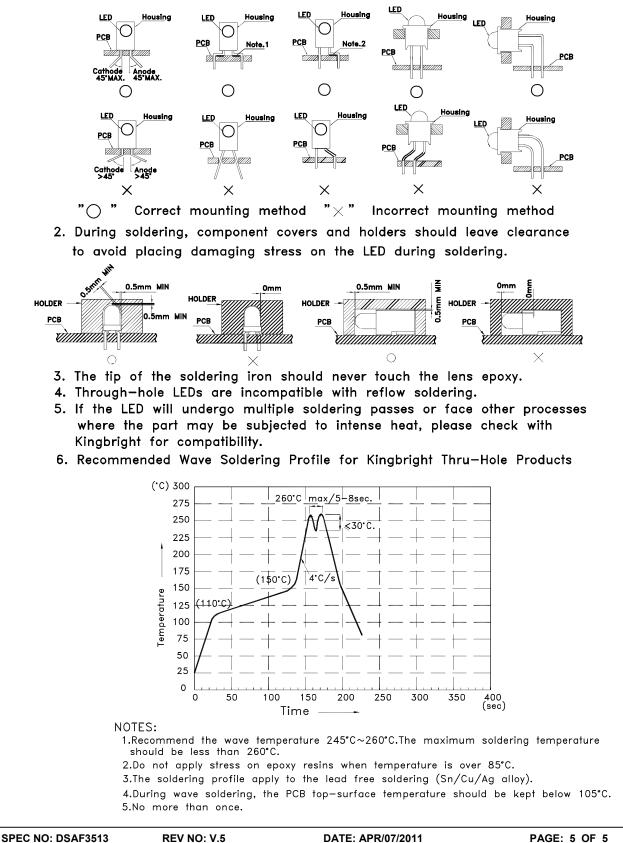
1.1/10 Duty Cycle, 0.1ms Pulse Width.
2.2mm below package base.
3.5mm below package base.





PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



DATE: APR/07/2011 DRAWN: J.Yu